

PHOTOSENSITIVE RESIN COMPOSITION AND PHOTOSENSITIVE
ELEMENT USING THE RESIN COMPOSITION

Abstract of the Disclosure

To provide a photosensitive resin composition and a photosensitive element using the resin composition with excellent sensitivity and adhesion as well as high resolution and plating resistance. A photosensitive resin composition, comprises (A) a polymer carrying carboxyl groups, (B) a compound carrying at least one ethylene-based unsaturated group in the molecule, and (C) a photopolymerization initiator, characterized by the fact that component (B) contains at least 60 weight % of methacrylate (B1) carrying at least one ethylene-based unsaturated group with respect to the total amount of component (B), that the amount of component (C) is in the range of 0.01 - 20 weight units with respect to 100 weight units of component (A) and component (B), and that component (C) contains 2 - 5 weight units of lophine dimer (C1) and 0.1 - 2.0 weight units of triphenylphosphine (C2) with respect to 100 weight units of component (A) and component (B), as well as a photosensitive element using the resin composition.